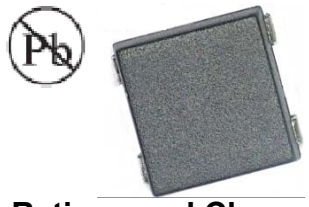
Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- Low Leakage Current
- High Forward Surge Capability
- Designed for Surface Mount Application
- Plastic Material - UL Flammability 94V -O

NEW PRODUCT RELEASE

PATENT PENDING



Mechanical Date

- **Case:**TLM-J Molded Plastic
- **Terminals:** Solder plated, Solderable per J-STD-002B and JESD22-B102D
- **Polarity:** As Marked on body
- **Marking:** Type Number
- **Lead Free:** For ROHS/Leadfree Version

Major Ratings and Characteristics

$I_{F(AV)}$	**0.5A,0.8 A**
V_{RRM}	**50 V to 1000 V**
I_{FSM}	**20 A**
I_R	**5 μA**
V_F	**1.1 V**
T_j max.	**150 °C**

Maximum Ratings & Thermal Characteristics (T_A = 25 °C unless otherwise noted)

Single Phase,half wave,60Hz,resistive or inductive load.

For capacitive load,derate current by 20%.

Items	Symbol	LX005M	LX01M	LX02M	LX04M	LX06M	LX08M	LX10M	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	0.5[1)]							A
		0.8[2)]							
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	20							A
Operating junction and storage temperature range	T_J, T_{STG}	–55 to +150							℃

1):Mounted on glass epoxy P.C.B with 1.2×1.5mm^2 pads。

2):Mounted on aluminum substrate P.C.B with 1.2×1.5mm^2 pads。

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

Items	Test conditions	Symbol	Min	Type	Max	
Instantaneous forward voltage	I_F=0.5A[3)]	V_F	-	0.95	1.1	V
Reverse current	T_A = 25 ℃	I_R	-	-	5	μA
	T_A = 125 ℃		-	-	100	

3):Pulse test: 300μS pulse width,1% duty cycle.

Characteristic Curves (T_A=25 ℃ unless otherwise noted)

Fig.1 Forward Current Derating Curve

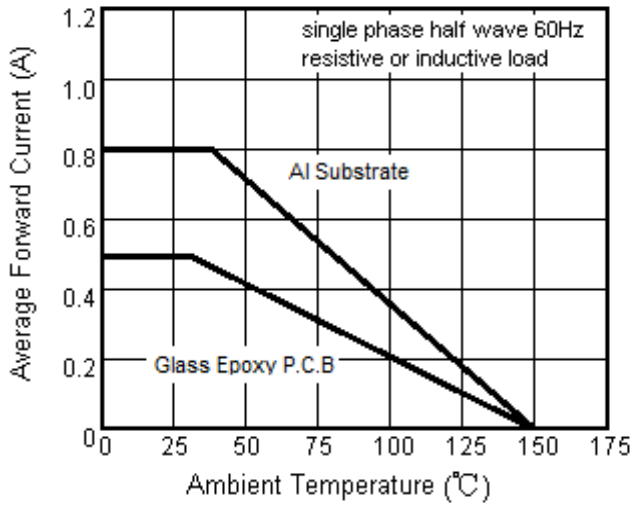


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

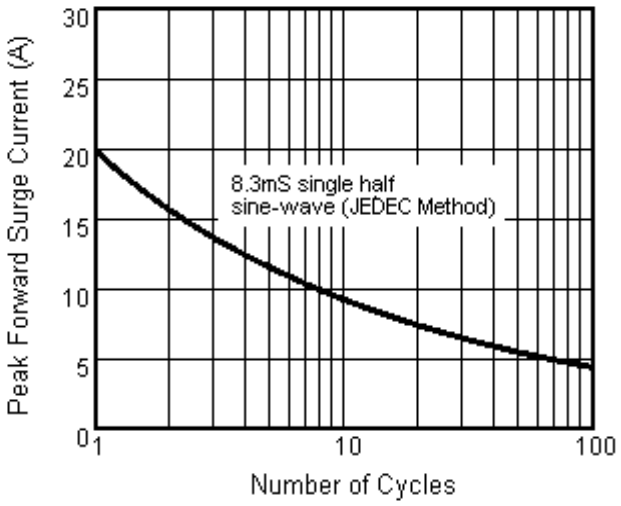


Fig.3 Typical Instantaneous Forward Characteristics

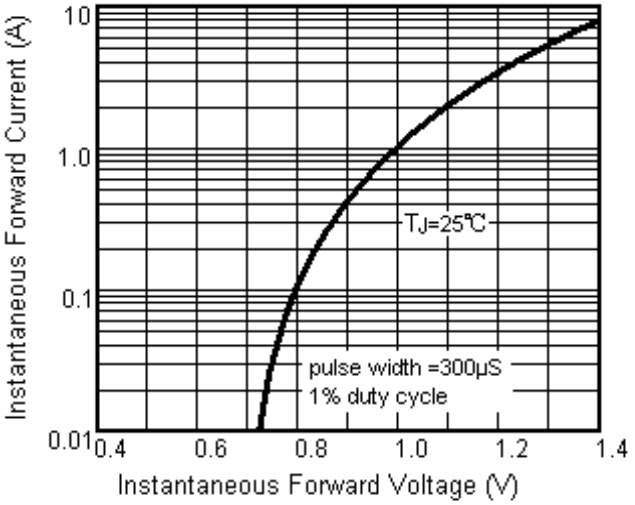
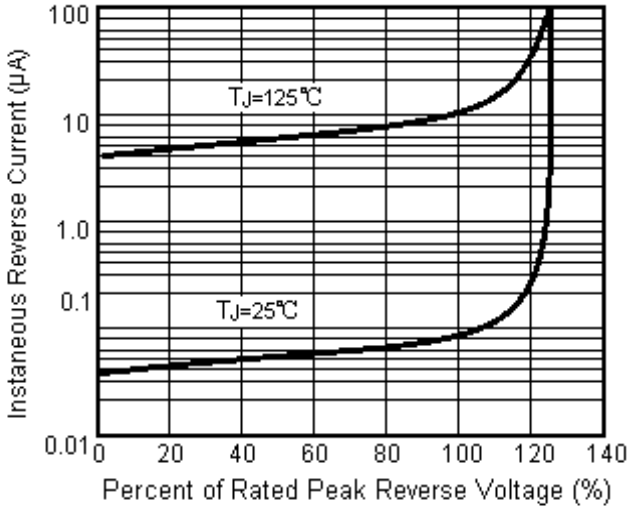
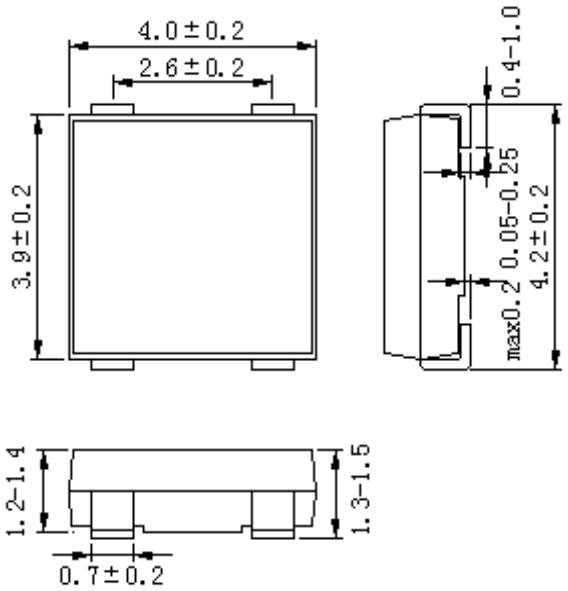


Fig.4 Typical Reverse Characteristics



Package Outline



Soldering Pad

